

SN74LV1T126, 具有三态输出的单电源单缓冲器门 CMOS 逻辑电平转换器

1 特性

- 电压为 5.0/3.3/2.5/1.8V 的单电源电压转换器 V_{CC}
- 1.8V 至 5.5V 的工作电压范围
- 上行转换
 - 1.8V V_{CC} 时, 1.2V⁽¹⁾ 至 1.8V
 - 2.5V V_{CC} 时, 1.5V⁽¹⁾ 至 2.5V
 - 3.3V V_{CC} 时, 1.8V⁽¹⁾ 至 3.3V
 - 5.0V V_{CC} 时, 3.3V 至 5.0V
- 下行转换
 - 1.8V V_{CC} 时, 3.3V 至 1.8V
 - 2.5V V_{CC} 时, 3.3V 至 2.5V
 - 3.3V V_{CC} 时, 5.0V 至 3.3V
- 逻辑输出以 V_{CC} 为基准
- 输出驱动
 - 5.0V 时, 8.0mA 的输出驱动
 - 3.3V 时, 7.0mA 的输出驱动
 - 1.8V 时, 3.0mA 的输出驱动
- 3.3V V_{CC} 时, 频率高达 50MHz
- 输入引脚上可耐受 5.0V 电压
- -40°C 至 125°C 工作温度范围
- 锁断性能超过 250mA
符合 JESD 17 规范
- 静电放电 (ESD) 性能测试符合 JESD 22 规范
 - 2000V 人体模型 (A114-B, II 类)
 - 200V 机器模型 (A115-A)
 - 1000V 充电器件模型 (C101)
- 支持标准逻辑引脚分配
- 与 AUP1G 和 LVC1G 系列兼容的 CMOS 输出 B

⁽¹⁾ 请参考更低 V_{CC} 条件下的 V_{IH}/V_{IL} 和输出驱动。

2 应用范围

- 工业用控制器
- 电信
- 便携式应用
- 服务器
- 个人电脑和笔记本电脑
- 汽车

3 说明

SN74LV1T126 是一款具有较宽电压范围的低压 CMOS 门逻辑电路, 用于工业、便携、电信和汽车应用。输出电平以电源电压为基准, 并且能够支持 1.8V/2.5V/3.3V/5V CMOS 电平。

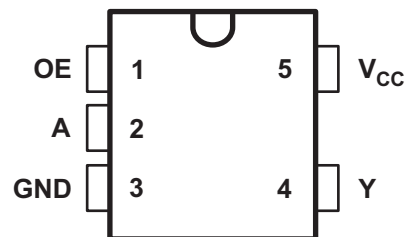
采用了更低阈值电路来设计此输入, 以便匹配 $V_{CC} = 3.3V$ 时的 1.8V 输入逻辑, 并且可被用于 1.8V 至 3.3V 电平上行转换。此外, 5V 容限输入引脚可实现下行转换 (例如, $V_{CC} = 2.5V$ 时的 3.3V 至 2.5V 输出转换)。1.8V 至 5.5V 的宽 V_{CC} 范围可使所需输出电平的生成接至控制器或处理器。

SN74LV1T126 被设计成具有 8mA 的电流驱动能力, 以减少由高驱动输出导致的线路反射、过冲和下冲。

器件信息

| 订货编号 | 封装 | 封装尺寸 |
|-----------------|-------------------------|-----------------|
| SN74LV1T126DBVR | 小外形尺寸晶体管封装 (SOT)-23 (5) | 2.90mm x 1.60mm |
| SN74LV1T126DCKR | SC70 (5) | 2.00mm x 1.25mm |

DCK or DBV PACKAGE (TOP VIEW)



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4 修订历史记录

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (December 2013) to Revision A

Page

| | | |
|---|----------------|----------|
| • | 已更新文档格式。 | 1 |
|---|----------------|----------|

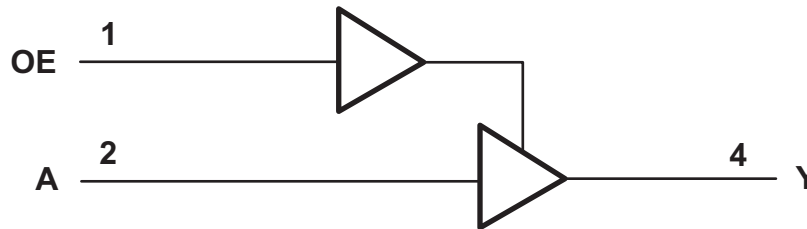
Function Table

| INPUT (Lower Level Input) | | OUTPUT (V _{CC} CMOS) |
|------------------------------|---|----------------------------------|
| OE ⁽¹⁾ | A | Y |
| H | H | H |
| H | L | L |
| L | X | Z |

(1) Not recommend to floating OE pin for signal oscillation

| SUPPLY V _{CC} = 3.3V | | |
|---|---|--|
| INPUT (Lower Level Input) | | OUTPUT (V _{CC} CMOS) |
| A | B | Y |
| V _{IH} (min) = 1.35 V V _{IL} (max) = 0.8 V | | V _{OH} (min) = 2.9 V V _{OL} (max) = 0.2 V |

4.1 Logic Diagram



Switching Characteristics at 50 MHz

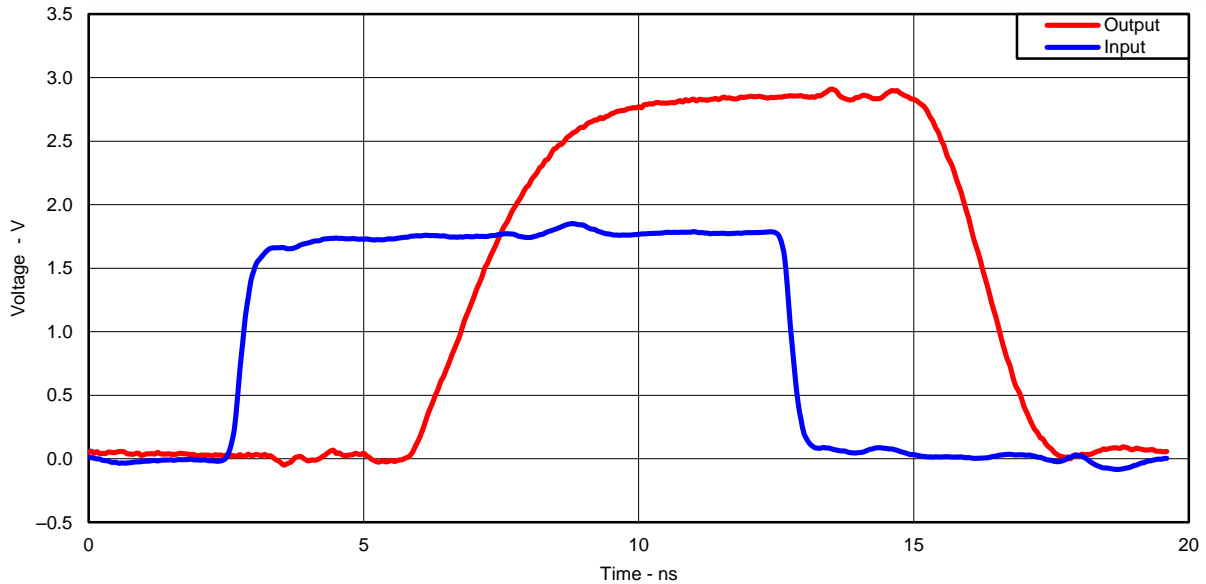


Figure 1. Excellent Signal Integrity (1.8V to 3.3V at 3.3V V_{CC})

Logic Diagram (continued)

Switching Characteristics at 50 MHz

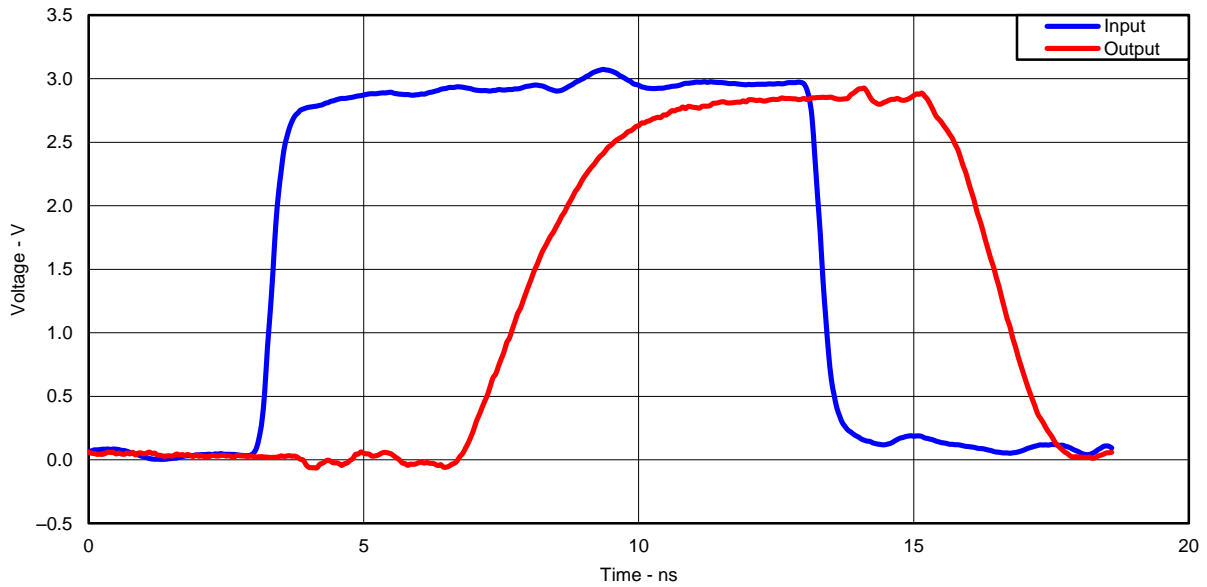


Figure 2. Excellent Signal Integrity (3.3V to 3.3V at 3.3V V_{CC})

Switching Characteristics at 15 MHz

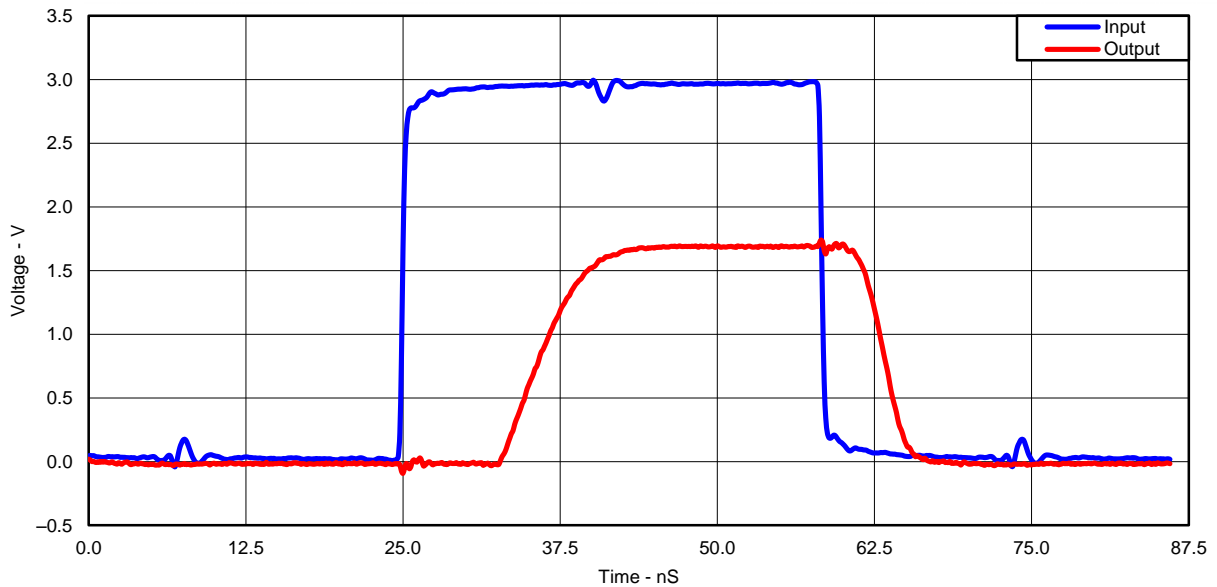


Figure 3. Excellent Signal Integrity (3.3V to 1.8V at 1.8V V_{CC})

4.2 Typical Design Examples

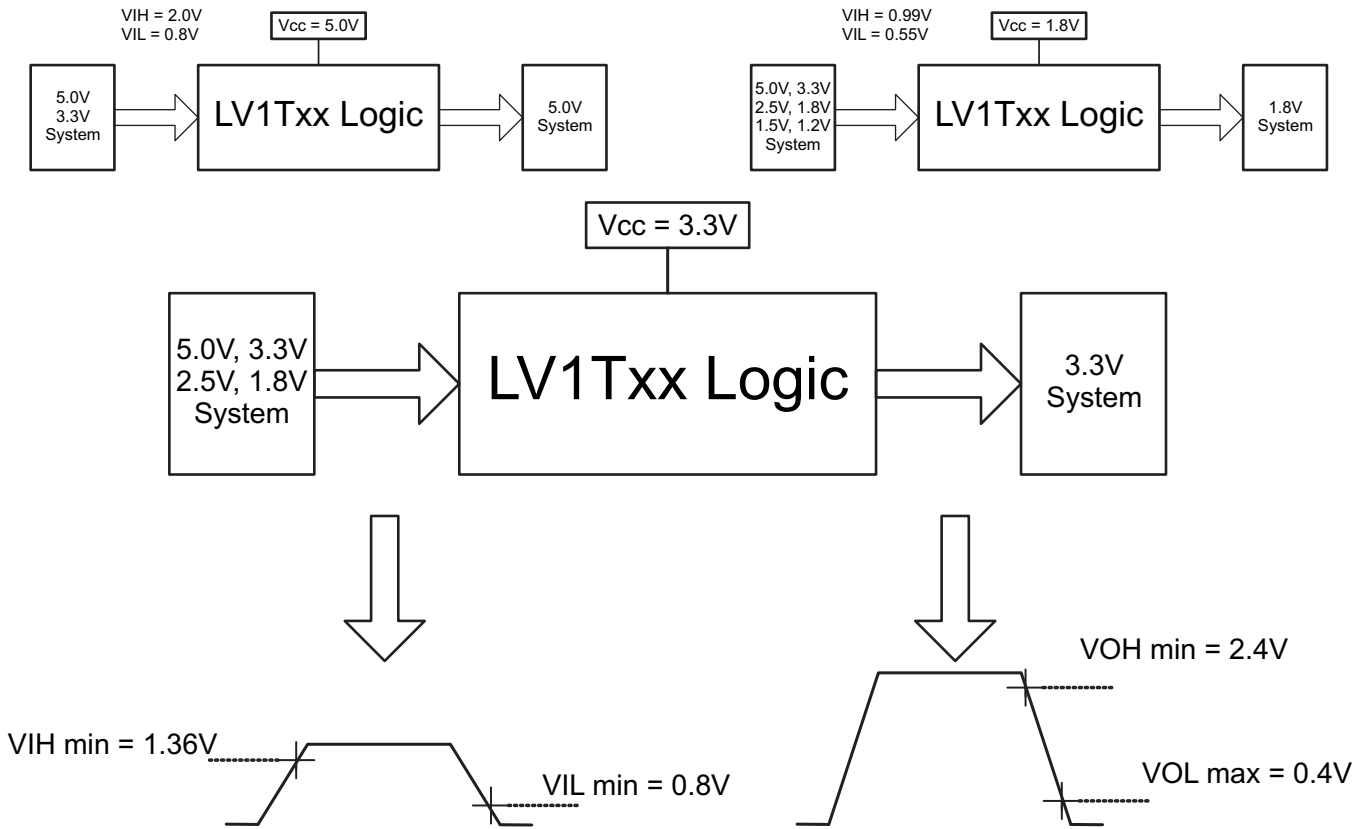


Figure 4. Switching Thresholds for 1.8-V to 3.3-V Translation

4.3 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT | |
|---------------|---|-----------------------------|----------------|------|------|
| V_{CC} | Supply voltage range | -0.5 | 7.0 | V | |
| V_I | Input voltage range ⁽²⁾ | -0.5 | 7.0 | V | |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | -0.5 | 4.6 | V | |
| | Voltage range applied to any output in the high or low state ⁽²⁾ | -0.5 | $V_{CC} + 0.5$ | V | |
| I_{IK} | Input clamp current | $V_I < 0$ | | -20 | mA |
| I_{OK} | Output clamp current | $V_O < 0$ or $V_O > V_{CC}$ | | ±20 | mA |
| I_O | Continuous output current | | | ±25 | mA |
| | Continuous current through V_{CC} or GND | | | ±50 | mA |
| θ_{JA} | Package thermal impedance ⁽³⁾ | DBV package | | 206 | °C/W |
| | | DCK package | | 252 | |
| T_{stg} | Storage temperature range | -65 | 150 | °C | |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

4.4 Recommended Operating Conditions⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT | |
|---------------------|------------------------------------|---------------------------|----------|------|------|
| V_{CC} | Supply voltage | 1.6 | 5.5 | V | |
| V_I | Input voltage | 0 | 5.5 | V | |
| V_O | Output voltage | 0 | V_{CC} | V | |
| I_{OH} | High-level output current | $V_{CC} = 1.8$ V | | -3.0 | mA |
| | | $V_{CC} = 2.5$ V | | -5.0 | |
| | | $V_{CC} = 3.3$ V | | -7.0 | |
| | | $V_{CC} = 5.0$ V | | -8.0 | |
| I_{OL} | Low-level output current | $V_{CC} = 1.8$ V | | 3.0 | mA |
| | | $V_{CC} = 2.5$ V | | 5.0 | |
| | | $V_{CC} = 3.3$ V | | 7.0 | |
| | | $V_{CC} = 5.0$ V | | 8.0 | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | $V_{CC} = 1.8$ V | | 20 | ns/V |
| | | $V_{CC} = 3.3$ V or 2.5 V | | 20 | |
| | | $V_{CC} = 5.0$ V | | 20 | |
| T_A | Operating free-air temperature | -40 | 125 | °C | |

- (1) All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

4.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | T _A = -40°C to 125°C | | UNIT |
|---|--|------------------------------------|-----------------------|------|-----|---------------------------------|-------|------|
| | | | MIN | TYP | MAX | MIN | MAX | |
| V _{IH} High-level input voltage | | V _{CC} = 1.65 V to 1.8 V | 0.95 | | | 1.0 | | V |
| | | V _{CC} = 2.0 V | 0.99 | | | 1.03 | | |
| | | V _{CC} = 2.25 V to 2.5 V | 1.145 | | | 1.18 | | |
| | | V _{CC} = 2.75 V | 1.22 | | | 1.25 | | |
| | | V _{CC} = 3.0 V to 3.3 V | 1.37 | | | 1.39 | | |
| | | V _{CC} = 3.6 V | 1.47 | | | 1.48 | | |
| | | V _{CC} = 4.5 V to 5.0 V | 2.02 | | | 2.03 | | |
| | | V _{CC} = 5.5 V | 2.1 | | | 2.11 | | |
| V _{IL} Low-level input voltage | | V _{CC} = 1.65 V to 2.0 V | | | | 0.57 | 0.55 | V |
| | | V _{CC} = 2.25 V to 2.75 V | | | | 0.75 | 0.71 | |
| | | V _{CC} = 3.0 V to 3.6 V | | | | 0.8 | 0.65 | |
| | | V _{CC} = 4.5 V to 5.5 V | | | | 0.8 | 0.8 | |
| V _{OH} | I _{OH} = -20 μA | 1.65 V to 5.5 V | V _{CC} - 0.1 | | | V _{CC} - 0.1 | | V |
| | I _{OH} = -2.0 mA | 1.65 V | 1.28 | | | 1.21 | | |
| | | 1.8 V | 1.5 | | | 1.45 | | |
| | I _{OH} = -3.0 mA | 2.3 V | 2.0 | | | 1.93 | | V |
| | I _{OH} = -3.0 mA | 2.5 V | 2.25 | | | 2.15 | | |
| | I _{OH} = -3.0 mA | 3.0 V | 2.78 | | | 2.7 | | |
| | I _{OH} = -5.5 mA | | 2.6 | | | 2.49 | | |
| | I _{OH} = -5.5 mA | 3.3 V | 2.9 | | | 2.8 | | |
| | I _{OH} = -4.0 mA | 4.5 V | 4.2 | | | 4.1 | | |
| | I _{OH} = -8.0 mA | | 4.1 | | | 3.95 | | |
| I _{OH} = -8.0 mA | 5.0 V | 4.6 | | | 4.5 | | | |
| V _{OL} | I _{OL} = 20.0 μA | 1.65 V to 5.5 V | | | | 0.1 | 0.1 | V |
| | I _{OL} = 2.0 mA | 1.65 V | | | | 0.2 | 0.25 | |
| | I _{OH} = 3.0 mA | 2.3 V | | | | 0.15 | 0.2 | |
| | I _{OL} = 3.0 mA | 3.0 V | | | | 0.11 | 0.15 | |
| | I _{OL} = 5.5 mA | | | | | 0.21 | 0.252 | |
| | I _{OL} = 4.0 mA | 4.5 V | | | | 0.15 | 0.2 | |
| | I _{OL} = 8.0 mA | | | | | 0.3 | 0.35 | |
| I _I A input | V _I = 0 V or V _{CC} | 0 V, 1.8 V, 2.5 V, 3.3 V, 5.5 V | | | | 0.1 | ±1.0 | μA |
| I _{CC} | V _I = 0 V or V _{CC} ; I _O = 0; Open on loading | 5.0 V | | | | 1.0 | 10.0 | μA |
| | | 3.3 V | | | | 1.0 | 10.0 | |
| | | 2.5 V | | | | 1.0 | 10.0 | |
| | | 1.8 V | | | | 1.0 | 10.0 | |
| ΔI _{CC} | One input at 0.3 V or 3.4 V Other inputs at 0 or V _{CC} , I _O = 0 | 5.5 V | | | | 1.35 | 1.5 | mA |
| | One input at 0.3 V or 1.1 V Other inputs at 0 or V _{CC} , I _O = 0 | 1.8 V | | | | 10.0 | 10.0 | μA |
| C _i | V _I = V _{CC} or GND | 3.3 V | 2.0 | 10.0 | 2.0 | 10.0 | pF | |
| C _o | V _O = V _{CC} or GND | 3.3 V | 2.5 | | 2.5 | | pF | |

4.6 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

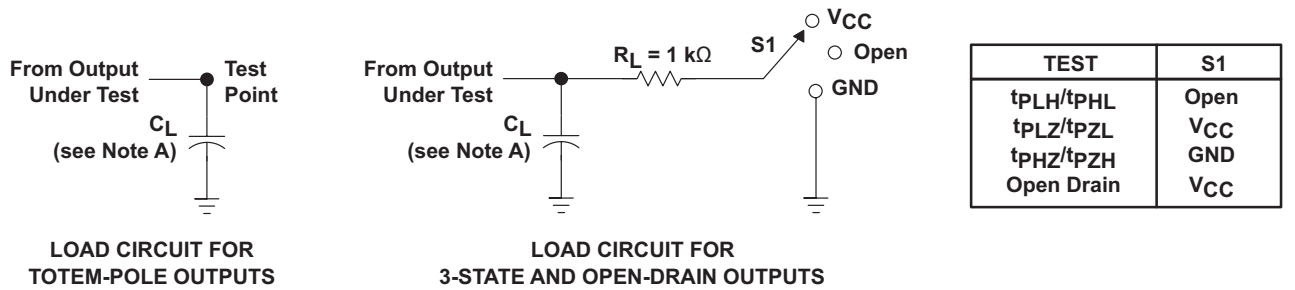
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | FREQUENCY (TYP) | V _{CC} | C _L | T _A = 25°C | | | T _A = -65°C to 125°C | | | UNIT |
|-------------------------------------|--------------|-------------|-----------------|-----------------|----------------|-----------------------|------|------|---------------------------------|-----|-----|------|
| | | | | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| t _{pd} | Any In | Y | DC to 50 MHz | 5.0 V | 15 pF | 2.7 | 5.5 | 3.4 | 6.5 | ns | | |
| | | | | | 30 pF | 3.0 | 6.5 | 4.1 | 7.5 | | | |
| | | | | 3.3 V | 15 pF | 4.0 | 7.0 | 5.0 | 8.0 | ns | | |
| | | | | | 30 pF | 4.9 | 8.0 | 6.0 | 9.0 | | | |
| | | | DC to 25 MHz | 2.5 V | 15 pF | 5.8 | 8.5 | 6.8 | 9.5 | ns | | |
| | | | | | 30 pF | 6.5 | 9.5 | 7.5 | 10.5 | | | |
| | | | DC to 15 MHz | 1.8 V | 15 pF | 10.5 | 13.0 | 11.8 | 14.0 | ns | | |
| | | | | | 30 pF | 12.0 | 14.5 | 12.0 | 15.5 | | | |
| t _{PZH} , t _{PZL} | OE | Y | DC to 50 MHz | 5.0 V | 15 pF | 3.0 | 5.0 | 3.5 | 6.0 | ns | | |
| | | | | | 30 pF | 4.3 | 6.5 | 4.9 | 7.5 | | | |
| | | | | 3.3 V | 15 pF | 4.0 | 6.5 | 4.5 | 7.5 | ns | | |
| | | | | | 30 pF | 5.0 | 8.0 | 6.5 | 9.0 | | | |
| | | | DC to 25 MHz | 2.5 V | 15 pF | 5.5 | 8.0 | 6.1 | 9.0 | ns | | |
| | | | | | 30 pF | 7.0 | 10.0 | 8.5 | 11.0 | | | |
| | | | DC to 15 MHz | 1.8 V | 15 pF | 9.0 | 12.0 | 9.85 | 13.0 | ns | | |
| | | | | | 30 pF | 12.5 | 15.0 | 13.5 | 16.0 | | | |
| t _{PHZ} , t _{PLZ} | OE | Y | DC to 50 MHz | 5.0 V | 15 pF | 4.2 | 6.5 | 4.5 | 7.0 | ns | | |
| | | | | | 30 pF | 4.8 | 8.0 | 5.0 | 8.5 | | | |
| | | | | 3.3 V | 15 pF | 4.5 | 7.0 | 5.0 | 8.0 | ns | | |
| | | | | | 30 pF | 5.0 | 8.0 | 5.5 | 9.0 | | | |
| | | | DC to 25MHz | 2.5 V | 15 pF | 5.0 | 11.0 | 6.0 | 9.0 | ns | | |
| | | | | | 30 pF | 6.0 | 9.0 | 7.0 | 10.0 | | | |
| | | | DC to 15MHz | 1.8 V | 15 pF | 8.0 | 10.0 | 8.5 | 11.0 | ns | | |
| | | | | | 30 pF | 8.5 | 11.0 | 9.5 | 12.0 | | | |

4.7 Operating Characteristics

over operating free-air temperature range (unless otherwise noted)

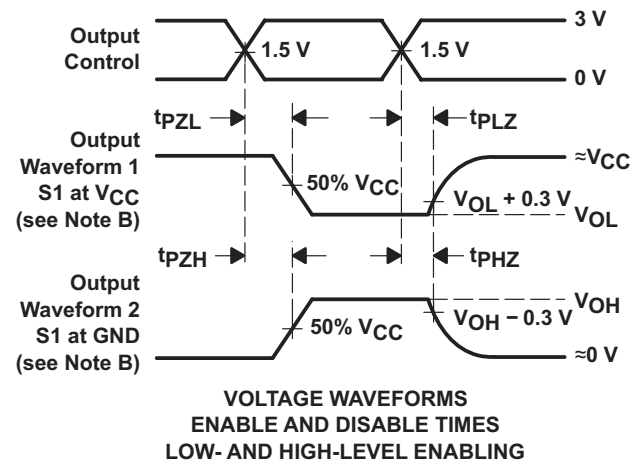
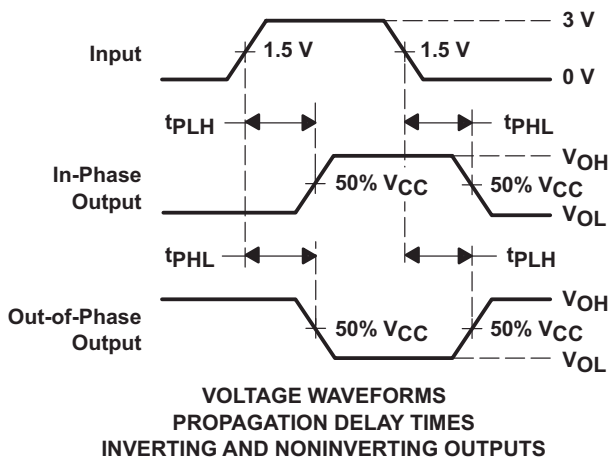
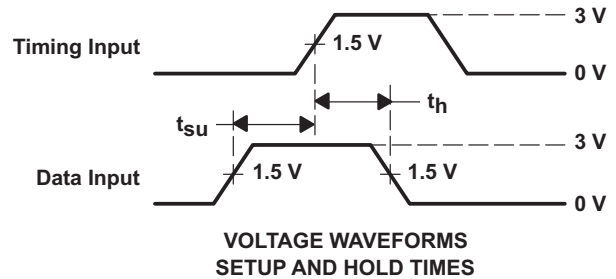
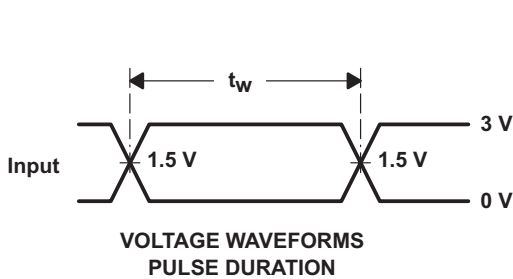
| PARAMETER | | TEST CONDITIONS | V _{CC} | TYP | UNIT |
|-----------------|-------------------------------|----------------------|-----------------|-----|------|
| C _{pd} | Power dissipation capacitance | f = 1 MHz and 10 MHz | 1.8 V ± 0.15 V | 14 | pF |
| | | | 2.5 V ± 0.2 V | 14 | |
| | | | 3.3 V ± 0.3 V | 14 | |
| | | | 5.0 V ± 0.5 V | 14 | |

5 Parameter Measurement Information



LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 5. Load Circuit and Voltage Waveforms

Parameter Measurement Information (continued)

5.1 More Product Selection

| DEVICE | PACKAGE | DESCRIPTION |
|-------------|---------------|--|
| SN74LV1T00 | DCK, DBV | 2-Input Positive-NAND Gate |
| SN74LV1T02 | DCK, DBV | 2-Input Positive-NOR Gate |
| SN74LV1T04 | DCK, DBV | Inverter Gate |
| SN74LV1T08 | DCK, DBV | 2-Input Positive-AND Gate |
| SN74LV1T126 | DCK, DBV, DPW | Single Buffer Gate |
| SN74LV1T14 | DCK, DBV | Single Schmitt-Trigger Inverter Gate |
| SN74LV1T32 | DCK, DBV | 2-Input Positive-OR Gate |
| SN74LV1T86 | DCK, DBV | Single 2-Input Exclusive-Or Gate |
| SN74LV1T125 | DCK, DBV | Single Buffer Gate with 3-state Output |
| SN74LV1T126 | DCK, DBV | Single Buffer Gate with 3-state Output |
| SN74LV4T125 | RGY, PW | Quadruple Bus Buffer Gate With 3-State Outputs |

6 器件和文档支持

6.1 Trademarks

All trademarks are the property of their respective owners.

6.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

7 机械，封装和可订购信息

下列封装信息和附录反映了针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。

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PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74LV1T126DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (NEN3 ~ NENS) | Samples |
| SN74LV1T126DCKR | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (WN3 ~ WNS) | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LV1T126DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.2 | 3.3 | 3.23 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LV1T126DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LV1T126DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LV1T126DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LV1T126DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LV1T126DBVR | SOT-23 | DBV | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LV1T126DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LV1T126DCKR | SC70 | DCK | 5 | 3000 | 202.0 | 201.0 | 28.0 |

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DBV (R-PDSO-G5)

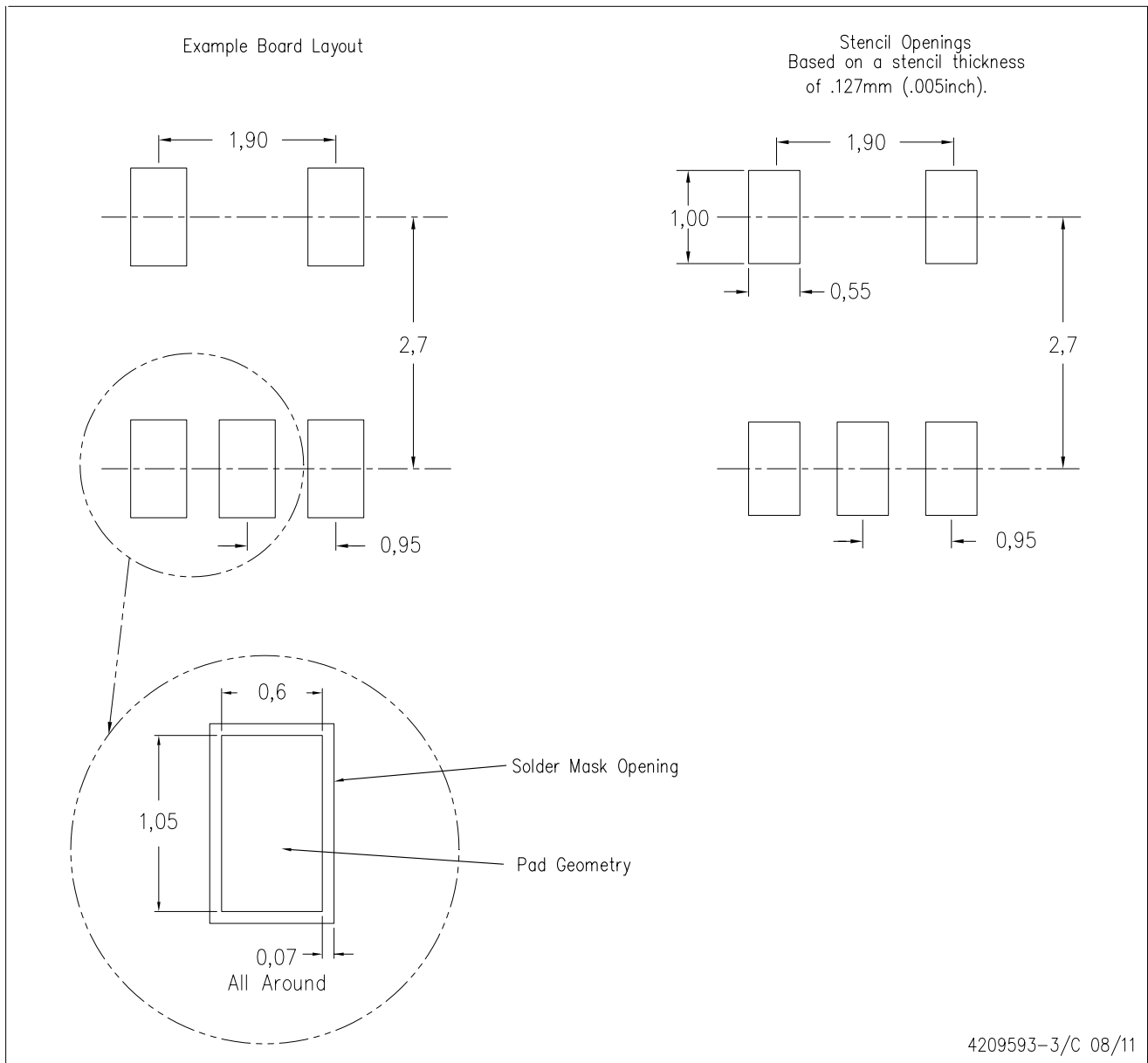
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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